

November 2014

ISL9R460PF2 4 A, 600 V, STEALTH™ Diode

Features

- Stealth Recovery t_{rr} = 17 ns (@ I_F = 4 A)
- Max Forward Voltage, V_F = 2.4 V (@ T_C = 25°C)
- 600 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- RoHS Compliant

Applications

- SMPS
- · Hard Switched PFC Boost Diode

CATHODE

- UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

Description

The ISL9R460PF2 is a STEALTH™ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH™ family exhibits low reverse recovery current (I_{rr}) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I_{rr} and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Package Symbol





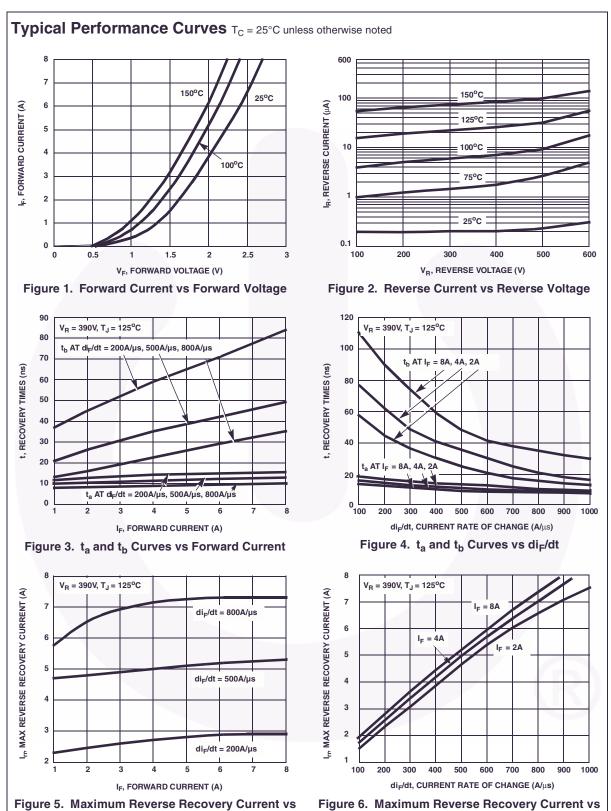


Device Maximum Ratings T_C= 25°C unless otherwise noted

Symbol	Parameter	Ratings	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	600	V
V _{RWM}	Working Peak Reverse Voltage	600	V
V _R	DC Blocking Voltage	600	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 108°C)	4	Α
I _{FRM}	Repetitive Peak Surge Current (20kHz Square Wave)	8	Α
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	50	Α
P _D	Power Dissipation	22	W
E _{AVL}	Avalanche Energy (0.5 A, 80 mH)	10	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
TL	Maximum Temperature for Soldering	300	°C
T_{PKG}	Leads at 0.063in (1.6mm) from Case for 10s	260	°C
	Package Body for 10s, See Techbrief TB334		

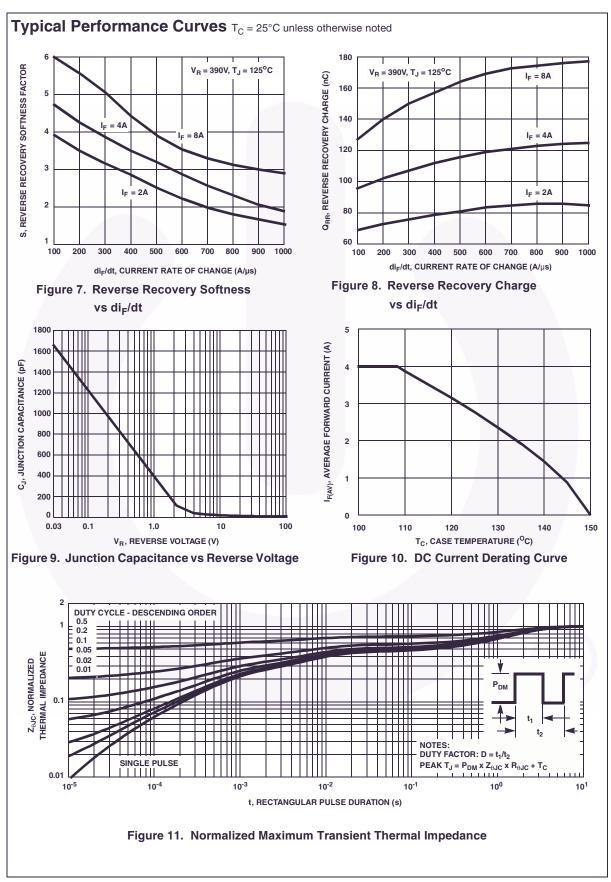
CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Packag	e M	arking and	l Ordering I	nformation					
Part Num	ber	Top Mark	Package	Packing Method	Reel Size	Tape	Width	Qı	antity
ISL9R460PF2		ISL9R460PF2	TO-220F-2L	Tube	N/A	N/A		50	
Electric	al C	Characteris	stics T _C = 25°C	unless otherwise note	d				
Symbol Parameter			Test Conditions		Min	Тур	Max	Unit	
Off State	Cha	aracteristics							-
I _B Ins		nstantaneous Reverse Current		V _R = 600 V	T _C = 25°C	-	-	100	μА
					T _C = 125°C	-	-	1.0	mA
On State	Cha	racteristics							
	Insta	nstantaneous Forward Voltage		I _F = 4 A	T _C = 25°C	_	2.0	2.4	V
				F	$T_C = 125^{\circ}C$	-	1.6	2.0	V
Dynamic	Cha	aracteristics				•	•		•
CJ	Juno	tion Capacitance		V _R = 10 V, I _F = 0 A		-	19	-	pF
Switchin	g Ch	naracteristics	3						
t _{rr}	Reverse Recovery Time		me	$I_F = 1 \text{ A, } di_F/dt = 100 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$		-	17	20	ns
				$I_F = 4 \text{ A}, dI_F/dt = 100$	$I_F = 4 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		19	22	ns
t _{rr}	Reve	everse Recovery Time		$I_F = 4 \text{ A},$ $di_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 390 \text{ V}, T_C = 25^{\circ}\text{C}$		-	17	-	ns
I _{rr}	Reve	Reverse Recovery Current				-	2.6	-	Α
Q _{rr}	Reve	everse Recovered Charge				-	22	-	nC
t _{rr}	Reve	Reverse Recovery Time		$ \begin{aligned} &I_F = 4 \text{ A,} \\ &\text{di}_F/\text{dt} = 200 \text{ A/}\mu\text{s,} \\ &\text{V}_R = 390 \text{ V,} \\ &-\text{T}_C = 125^{\circ}\text{C} \end{aligned} $		-	77	-	ns
S	Softr	Softness Factor (t _b /t _a)				-	4.2	-	
I _{rr}	Reve	Reverse Recovery Current Reverse Recovered Charge				-	2.8	-	А
Q _{rr}	Reve					-	100	-	nC
t _{rr}	Reve	erse Recovery Ti	me	I _F = 4 A,		-	54	-	ns
S	Softr	Softness Factor (t _b /t _a) Reverse Recovery Current Reverse Recovered Charge		$di_F/dt = 400 \text{ A/}\mu\text{s},$ $V_R = 390 \text{ V},$ $T_C = 125^{\circ}\text{C}$		-	3.5	-	
I _{rr}	Reve					-	4.3	-	Α
Q _{rr}	Reve						110	-	nC
dI _M /dt	Maximum di/dt during t _b				-	500	-	A/µs	
Thermal	Cha	racteristics							
$R_{\theta JC}$	Ther	mal Resistance	Junction to Case			/ -	-	5.7	°C/W
$R_{\theta JA}$	Ther	mal Resistance	Junction to Ambier	nt TO-220F		-	-	70	°C/W

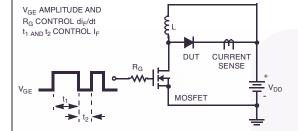


Forward Current

di_F/dt



Test Circuit and Waveforms



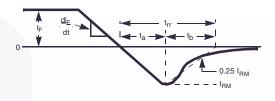
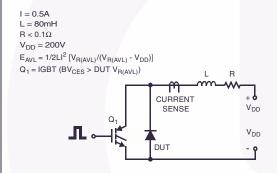


Figure 12. It_{rr} Test Circuit

Figure 13. t_{rr} Waveforms and Definitions



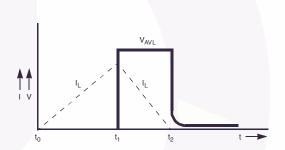


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

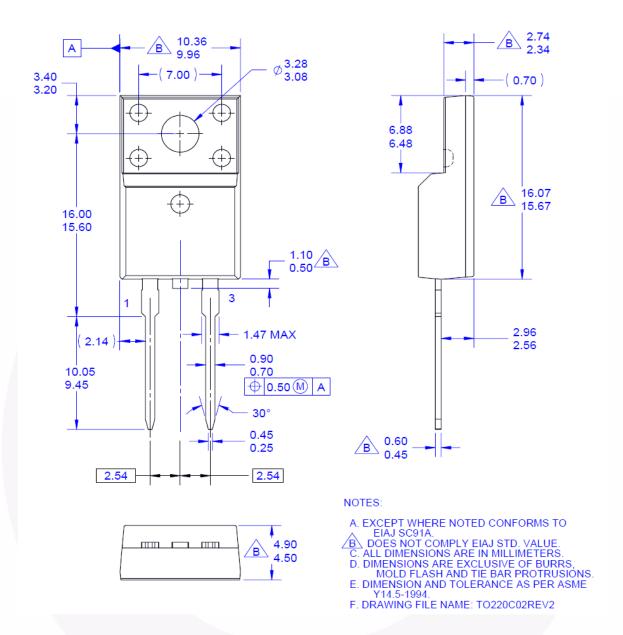


Figure 16. TO-220F 2L - 2LD; TO220; MOLDED; FULL PACK

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Rev. 171